

/ Descriptions

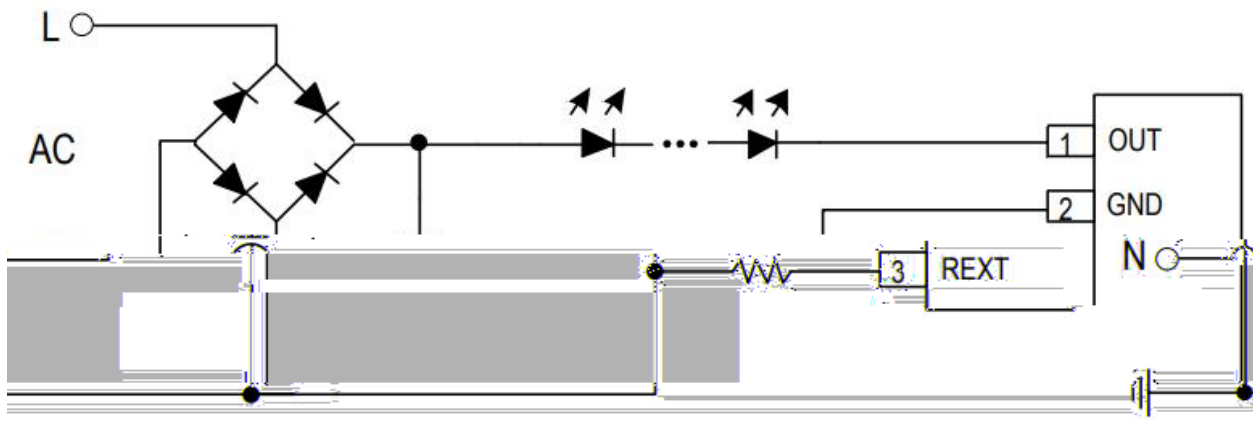
/ Features

- ◆
- ◆
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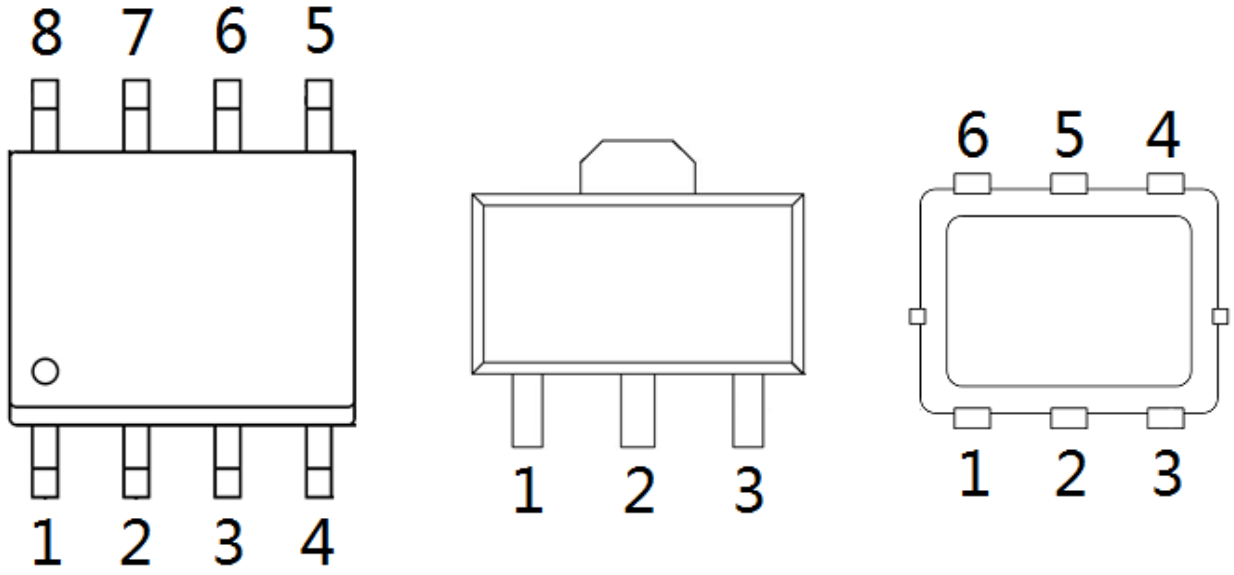
2

/ Applications

- ◆
- ◆
- ◆



/ Pinning



<JF G\$/	JF K\$/O	G; =E *2) \$ C	

/ Part Number

	J < <JF G\$/ K8 JF K\$/O PK G; =E *2) \$ C

/ Absolute Maximum Ratings(Ta=25)

	θ		
	θ		
2	θ		

Ω

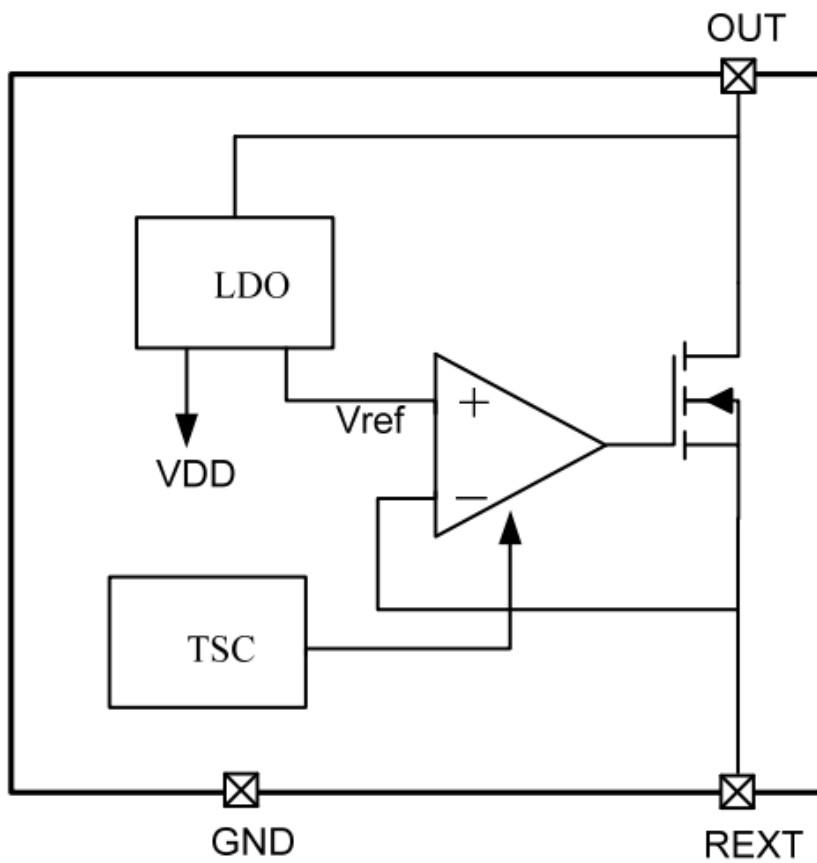
/ Working Range

2			

/ Electrical Characteristics($T_A=25$)

						μ
			2			
					\pm	

/ Functionl Block Diagram



/ Functional Description

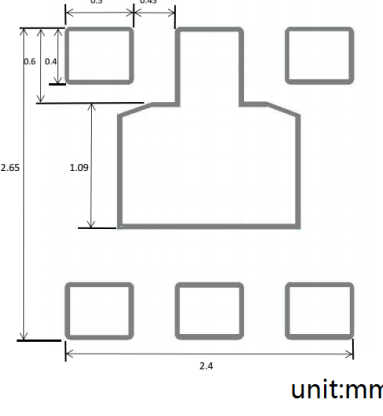
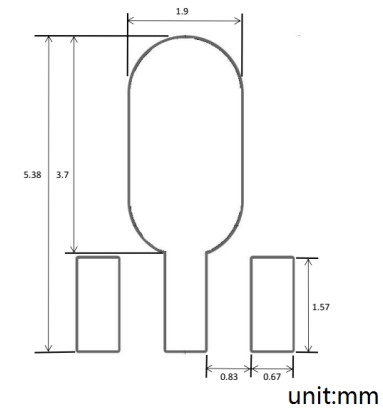
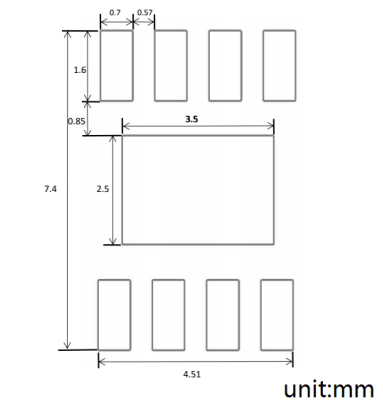
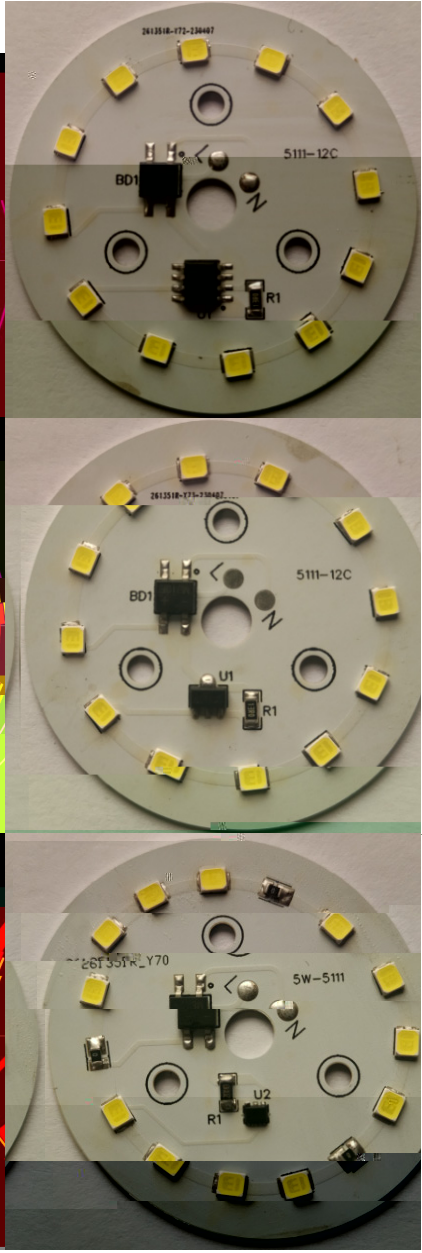
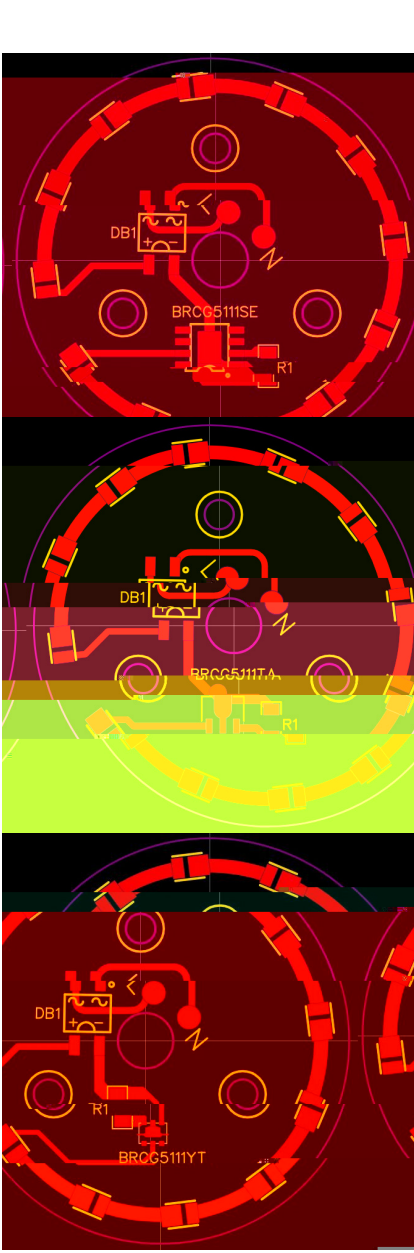
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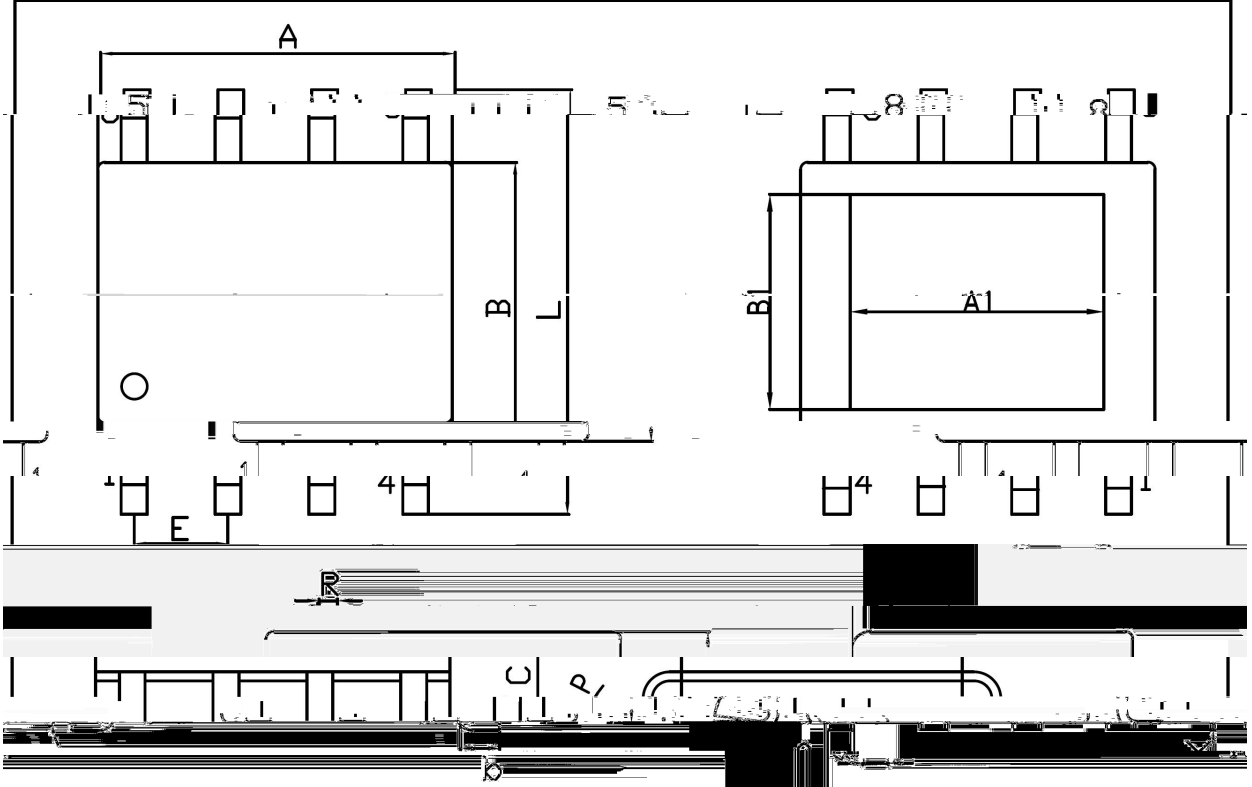
BRCG5111 Series

PCB & / PCB picture or Actual picture or Mounting pad size



/ Package Dimensions

ESOP-8 Unit:mm

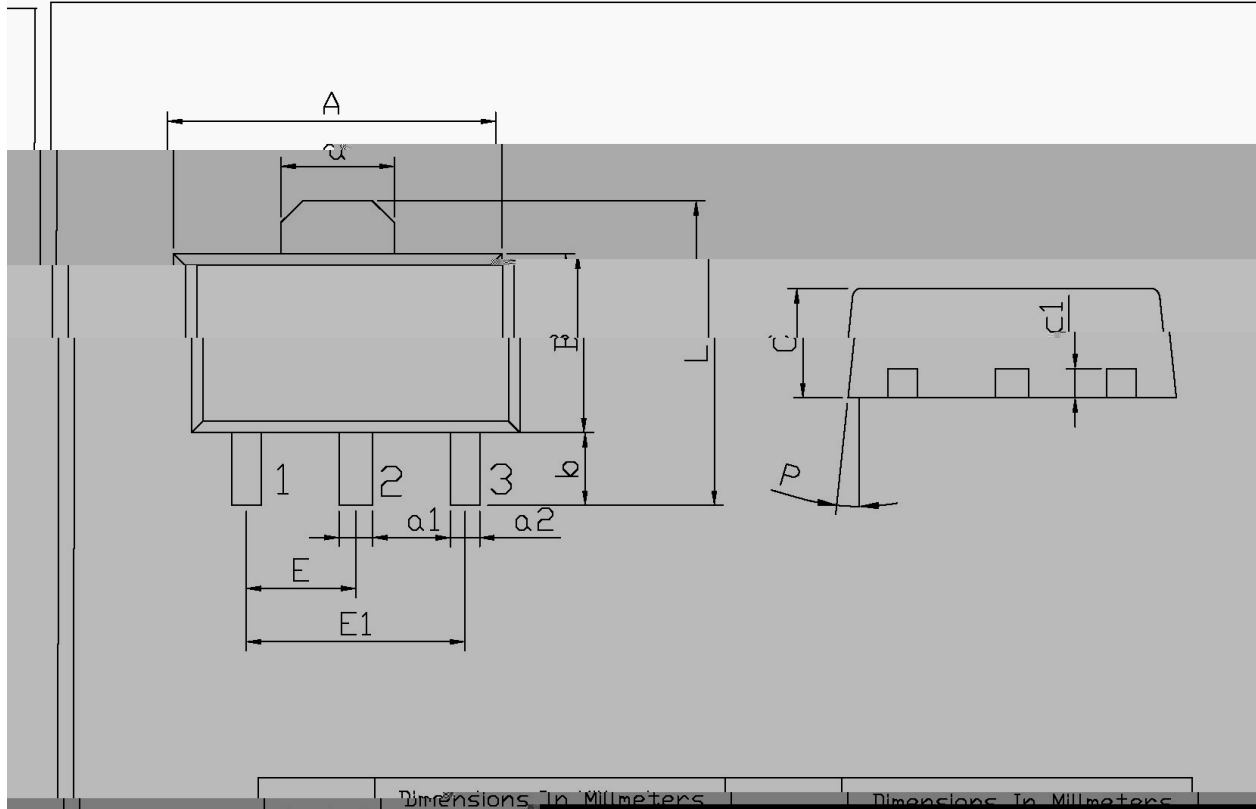


Symbol	Dimensions—in MILLIMETERS		Dimensions—in MILS	
	Min	Max	Min	Max
A	3.70	4.10	145	161
B	3.70	4.10	145	161
L	5.00	6.20	197	244
A1	2.1	2.5	83	100

/ Package Dimensions

1 2 3 4 5 6 7 8 9

单位: mm



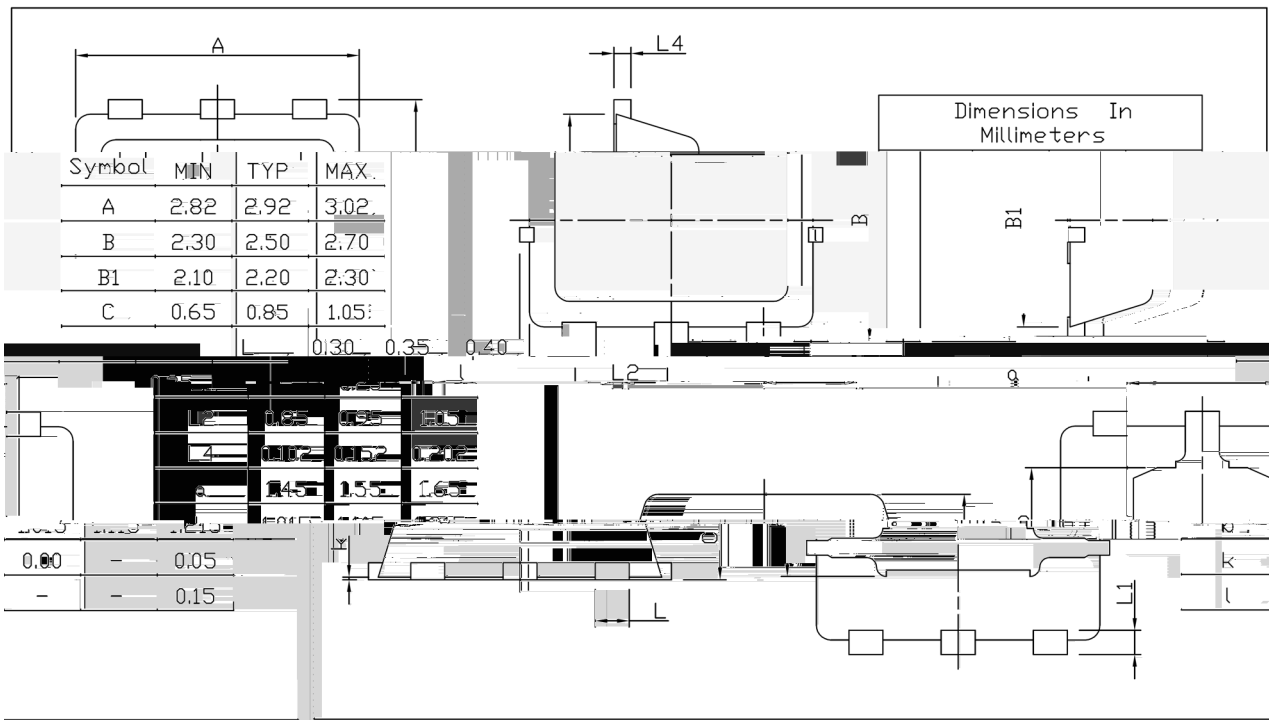
Dimensions In Millimeters

Dimensions In Millimeters

/ Package Dimensions

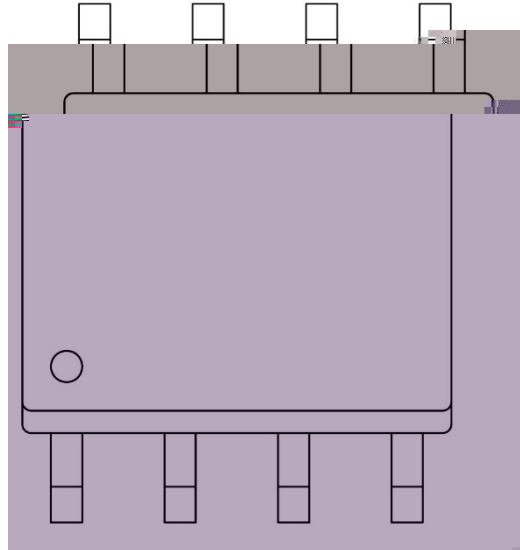
PDFN3 X2

Unit:mm



Rev.00 202208

/ Marking Instructions

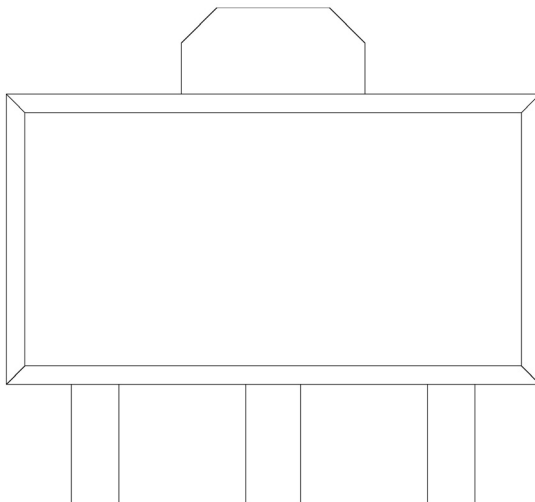


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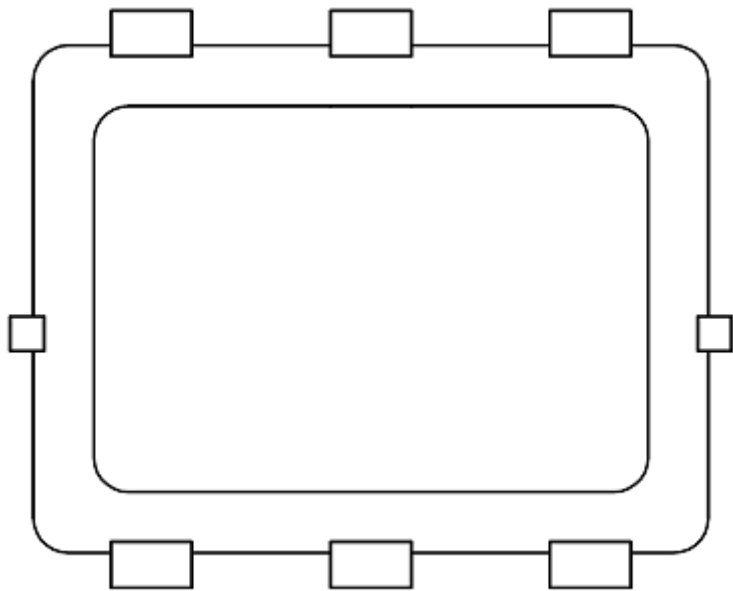
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/ Marking Instructions



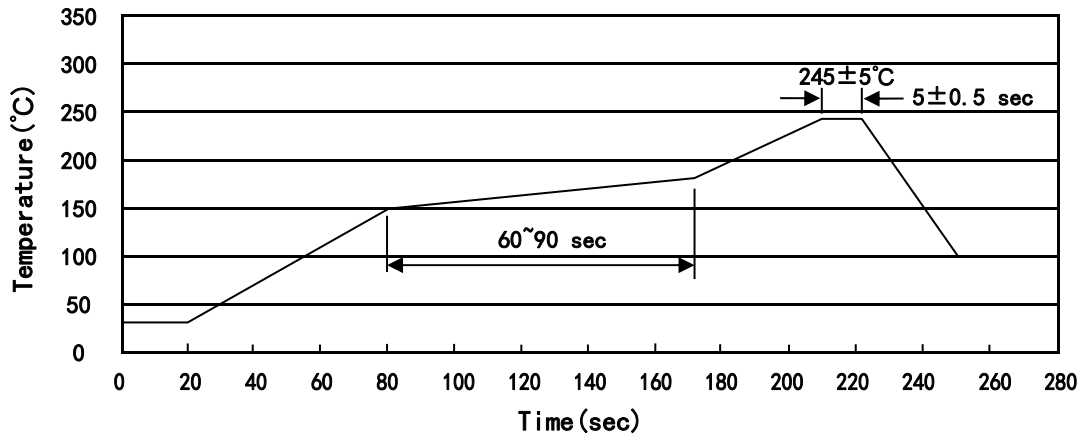
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/ Marking Instructions



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() / Temperature Profile for IR Reflow Soldering(Pb-Free)



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/ Resistance to Soldering Heat Test Conditions

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/ Packaging SPEC.

Package Type	Units				Dimension (unit: mm)		

/ Notices